

ATTACHMENT A

Claims 33-50 have been added, as shown below.

--33. The package of Claim 1, wherein the conductive inner leads are formed from an internal paddle area.

34. The package of Claim 33, further comprising means for securing and electrically isolating the conductive inner leads.

35. The package of Claim 33, wherein the first die is attached to the internal paddle area.

36. The package of Claim 33, wherein the first ends of the inner leads are closer to the die than the first ends of the outer leads.

37. The package of Claim 33, wherein the first ends of the inner leads extend beyond the second ends of the outer leads.

38. The package of Claim 33, wherein the first ends of the inner leads do not extend beyond the second ends of the outer leads.

39. A semiconductor die package, comprising:

a lead frame having external leads;

internal leads electrically isolated from the external leads and secured to the

lead frame;

means for securing and electrically isolating the internal leads from each other;
a die electrically coupled to the external leads and the internal leads; and
means for encapsulating the die and portions of the internal and external leads,
wherein the ends of the internal leads are exposed through a surface of the means for
encapsulating.

40. The package of Claim 39, wherein the internal leads are formed from an internal
paddle area.

41. The package of Claim 40, wherein the ends of the internal leads are exposed
through a bottom surface of the means for encapsulating.

42. The package of Claim 40, wherein the ends of the internal leads are exposed
through a top surface of the means for encapsulating.

43. The package of Claim 42, further comprising a second die package overlying the
die package and electrically coupled to the internal leads of the die contained within the die
package.

44. The package of Claim 40, wherein the ends of the internal leads are bent towards
the surface of the means for coupling.

45. The package of Claim 40, wherein the external leads have first ends extending
outside the means for encapsulating and second ends extending toward the die, and wherein
the second ends of the external leads extend beyond the ends of the internal leads.

46. A semiconductor die package, comprising:

a die;

an enclosure protecting the die;

external leads each having a first and a second end, wherein the first ends extend beyond the enclosure and the second ends are electrically coupled to the die; and

internal leads having at least first ends exposed through the enclosure, wherein the die is electrically coupled to the internal leads, and wherein the internal leads are electrically isolated from the external leads.

47. The package of Claim 46, wherein the first ends of the internal and external leads are approximately co-planar.

48. The package of Claim 46, where the first ends of the internal and external leads are located on opposite sides of the enclosure.

49. The package of Claim 48, further comprising a second die located over the die and electrically coupled to the first ends of the internal leads.

50. The package of Claim 46, wherein the first ends of the internal leads and the second ends of the external leads are interleaved.--